

In the Specification:

A' On page 1, lines 10-13, please delete the sentence, "More particularly, the invention relates to apparatus for performing *in situ* measurement of process parameters as a semiconductor wafer is processed by a semiconductor wafer processing system and a method of fabricating the apparatus."

On page 2, line 27, delete "randomly".

On page 2, lines 27 and 28, delete "instead of linearly polarized beams".

On page 3, line 5, delete "processed" and insert -processes- therefor.

On page 5, line 6, after "by" insert walls defining a processing enclosure capable of sustaining an environment suitable to process a substrate. The walls should, for example, be capable of maintaining a vacuum or low pressure environment in the chamber. The walls are defined by, for example,

On page 5, line 7, after "106" insert -or ceiling or top portion-.

On page 5, line 7, before "The chamber" insert -The ceiling 106 includes at least a portion that substantially faces the substrate, as shown in Figures 1-4.-.

On page 7, line 12, replace "over" with -other-.

On page 7, line 5, after "beams" insert -of radiation, for example light radiation,-.

On page 8, line 8, after "212" insert -that is external to the chamber processing environment-.

On page 8, line 11, after "212." insert -As can be seen in Figures 1-4, the antenna 210 covers at least a portion of the external surface 212 of the dome or ceiling 106 that substantially faces the substrate 110.-.

On page 9, line 32, after "beam" insert -of radiation, for example light radiation,-.

In the drawings

The drawing changes approved in the parent case have been incorporated into the present drawings.

**REMARKS**

The specification has been amended as in the parent case, Serial No. 08/944,240. The amendments add no new matter and entry is requested.